

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>				
<b>Filing Date:</b>				
<b>Title of Invention:</b>	Method of Forming Thin SGOI Wafers with High Relaxation and Low Stacking Fault Defect Density			
<b>First Named Inventor:</b>	Huajie Chen			
<b>Filer:</b>	Yuanmin Cai			
<b>Attorney Docket Number:</b>	FIS920030342US1			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
National Stage Fee	1631	1	300	300
Nat'l Stage Search - U.S. as IPE or ISA	1640	1	0	0
National Stage Exam Fee - U.S. was IPEA	1643	1	0	0
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				300